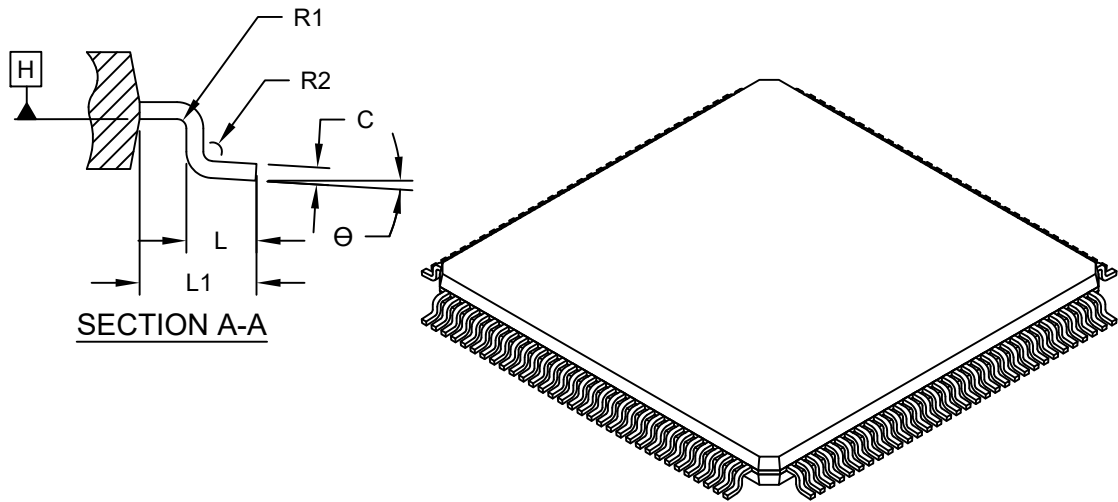


128-Lead Thin Plastic Quad Flatpack (Z2X) - 14x14 mm Body [TQFP]
SMSC Legacy VTQE3; Atmel Legacy Global Package Code APL

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	128		
Lead Pitch	e	0.40 BSC		
Overall Height	A	-	-	1.20
Standoff	A1	0.05	0.10	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	θ	0°	-	7°
Overall Width	E	16.00 BSC		
Overall Length	D	16.00 BSC		
Molded Package Width	E1	14.00 BSC		
Molded Package Length	D1	14.00 BSC		
Lead Width	b	0.13	0.16	0.23
Mold Draft Angle Top	C	0.09	-	0.20
Lead Bend Radius	R1	0.08	-	-
Lead Bend Radius	R2	0.08	-	0.20

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.